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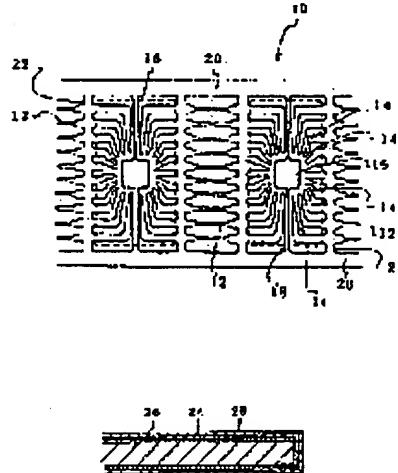
(21)Application number : 02-234833	(71)Applicant : SHINKO ELECTRIC IND CO LTD
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(54) LEAD FRAME FOR SEMICONDUCTOR DEVICE

(57)Abstract:

PURPOSE: To obtain a lead frame for a semiconductor device to improve solderability by Ag-plating a thin Pd or Pd alloy film or forming an Au-plated film.

CONSTITUTION: A Pd or Pd alloy film 24 is formed through a base plated film 26 such as Ni-plated film on the entire material of a lead frame 10, or formed directly on the material according to the quality of the material. An Ag plated or Au-plated film 28 is formed on the entire frame 10, or at least formed on outer leads 12, and the film 28 is formed in a thin film of the degree of a single atomic layer. Thus, solder wettability is improved, a wetting time can be shortened, excellent solderability can be provided, and soldering operability can be improved.



LEGAL STATUS

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